

#### **IPC-9797**

# Press-Fit Standard for Automotive Requirements and Other High-Reliability Applications

Developed by the Cold Joining Press-Fit Task Group (5-21m) of the Assembly and Joining Committee (5-20) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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IPC

### **Table of Contents**

1 Scc	ppe	1	2.1	IPC Documents	. 6
1.1	Purpose	1	2.2	Joint Industry Documents	. 7
1.2	Classification	1	2.3	JEDEC	. 7
1.3	Measurement Units	1	2.4	International Electrotechnical Commission	
1.3.1	Verification of Dimensions	1		Documents	
1.4	Definition of Requirements	1	2.5	ASTM	. 7
1.4.1	Acceptance Criteria	2	2.6	Automotive Industry Action Group Documents	7
1.5	Process Control Requirements	3	2.7	International Organization for Standardization	. /
1.6	Order of Precedence	3	2.1	(ISO)	. 7
1.6.1	Conflict	3	0 DE	OUIDEMENTO	_
1.6.2	Appendices	3	3 RE(	QUIREMENTS	
1.7	Use of "Lead"	3		Compliant Press-Fit Pin Requirements	
1.8	Abbreviations and Acronyms	3	3.1.1	Cleanliness Requirements	
1.9	Terms and Definitions	3	3.1.2	Design Requirements	. /
1.9.1	Compliant Press-Fit Pin Connection	3	3.1.3	Compliant Press-Fit Pin Contact Finish Requirements	. 8
1.9.2	Compliant Press-Fit Pin	3	3.2	Requirements for Printed Boards for Press-Fit	
1.9.3	Compliant Press-Fit Zone	3		Technology	. 8
1.9.4	Contact Area	4	3.2.1	Printed Circuit Board Design Requirements	. 8
1.9.5	Deposition of Surface Finishes	4	3.2.2	Material Requirements	. 9
1.9.6	Pad Lifting	4	3.2.3	Surface Finish	. 9
1.9.7	Pad Bulging	4	3.2.4	Printed Board Requirements for Qualification	
1.9.8	Laminate Buckling	4		and Test of Compliant Press-Fit Zones	. 9
1.9.9	Whitening		4 TES	STS	. 9
1.9.10	Intimate Metal to Metal Connection		4.1	General	. 9
1.9.11	Jet-Effect Deformation j		4.2	Unassembled Tests - Test Group A	12
1.9.12	Pin Shaft		4.2.1	Examination of Pin and Test-Printed Board	
1.9.13	Pin Neck			Dimensions – A1	
1.9.14	Pin Shoulder		4.2.2	Optical Inspection of Surface Condition – A2	
1.9.15	Compliant Press-Fit Zone Tip		4.2.3	Adhesion Test – A3	
1.9.16	Strip and Strip Thickness		4.2.4	Spring-Force Measurement – A4	
1.9.17	Push-In Force		4.2.5	Cross Sections of Pins and Printed Board – A5	
	Push-Out Force		4.3	Assembled Tests – Test Group B to F	
1.9.19	Pull-Out Force		4.3.1	Push-In and Measurement of Push-In Force – B1, C1, D1, E1, F1	
1.9.20	Push-Through Force		4.3.2	Storage – B2, C2, D2, E2	
1.9.21	Electrical Clearance		4.3.3	Optical Inspection on Protrusion and Insertion	
1.9.22	User			Side - B3, C3+C6, D3+D10, E3+E7	14
1.9.23	Manufacturer (Assembler)		4.3.4	Contact Resistance – B4, C4+C7, D4+D11,	- 1
1.9.24	Supplier		4.3.5	E4+E8  Push-Out and Measurement of Push-Out	14
1.10	Additional Requirements		4.3.3	Force – B5, C8, D12, E9	15
1.10.1	Requirements Flowdown		4.3.6	Transverse and Longitudinal Cross-Sections – B6, C9, D13, E10	15
1.10.2	Personnel Proficiency		4.4	Environmental Tests – Test Groups C, D, E	
1.11	Inspection Methodology	6	4.4.1	Temperature Cycle – C5, D5, E5	
1.11.1	Lighting	6	4.4.2	Climatic Sequence – D6	
1.11.2	Magnification Aids	6	4.4.3	High Temperature Storage – D7	
<b>2</b> ΔΡΙ	PLICABLE DOCUMENTS	6	4.4.4	Flowing Mixed Gas Corrosion Test – D8	
• •					

4.4.5	Vibra	ation Test – E6	18	Figure 5-6		21
4.5	Whis	sker Test	18	Figure 5-7		21
4.5.1 2000 H Storage - E2		18	Figure 5-8		21	
5 Ac	rentai	nce Criteria	19	Figure 5-9		22
5.1	-			Figure 5-10		22
5.1.1		esion		Figure 5-11	Cracking of Solder Resist	22
5.2		eptance Criteria for Test Groups B-E		Figure 5-12		23
5.2.1		cal Inspection		Figure 5-13		23
5.2.1		s-Sectional Criteria		Figure 5-14	Indications of Delamination (Whitening)	23
				Figure 5-15		24
5.3		hanical		Figure 5-16		24
5.3.1		n-In Force		Figure 5-17		24
5.3.2		n-Out Force		Figure 5-18		25
5.4		trical		Figure 5-19		25
5.4.1	Cont	tact Resistance	37	Figure 5-20		25
Appen	dix A	Abbreviations and Acronyms	38	Figure 5-21		26
		-		Figure 5-22		27
Appendix B Requirements for Aerospace Applications		30	Figure 5-23		27	
		Applications	00	Figure 5-24		27
		Figures		Figure 5-25		28
Figure	1-1	1 Schematic of Longitudinal (a) and Transverse	erse	Figure 5-26		28
9 -		(b) Cross-Section of a Compliant Press-Fi	t	Figure 5-27	j = 125 μm	28
		Connection.		Figure 5-28		
Figure	1-2	Examples of Interface Contacts, Compliant Press-Fit Pin and Plated-Through Hole		Figure 5-29		29
Figure	1 1			Figure 5-30		29
Figure 4-1		Elasticity Test Tool with Compliant Press-Fit Pin on the Left and Closed Tool on the Right		Figure 5-31		
		(drawing is not to scale).		Figure 5-32		
Figure	4-2	Corrective Curve.		Figure 5-33		
			13	Figure 5-34		
Figure	4-3	of a Press-Fit Joint	1.4	Figure 5-35		
<b>-</b> :	4 4		14	Figure 5-36		
Figure		est Setup for the 4-Point Resistance  Measurement	14	Figure 5-37		
Figure	4-5	Test Setup for the Push-Out Test		Figure 5-38		
Figure		Schematic Force Versus Distance/	10	Figure 5-39		
rigaro	7 0	Displacement Graph Obtained in A		Figure 5-40		
		Push-Out Test	15	Figure 5-41		
Figure	Cro	Indication of Plane for Transverse	4.5	Figure 5-42		
		Cross-Section	15	Figure 5-43		
Figure	4-8	Indication of Planes for Longitudinal Cross-Sections	16	rigure 5-45		00
Figure	<b>1</b> _0	Lateral PTH Deformation a and Remaining			Tables	
rigure		Metallization b Cross-Sections	•	Table 3-1	Examples of Common Press-Fit	
Figure		Remaining Metallization b, Deformation			Applications	7
O		of Inner Layers (Jet Effect) j and Whitening		Table 4-1	Test Sequence	10
		of Printed Board w		Table 4-2	Qualification Tests Required for Initial	
Figure		Cracks in Circles			Qualification and Changes in Production	
Figure			19	Table 4-3	Test Conditions for Temperature Cycle	
Figure	5-2		19	Table 5-1	Wisker Documentation	26
Figure 5-3		19	Table 5-2	Typical Minimum Push-Out Forces for Compliant Press-Fit Zone of Different Material Thickness Pertaining to Nominal		
Figure 5-4		20				
Figure	5-5		20		Hole Sizes	36

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## Press-Fit Standard for Automotive Requirements and Other High-Reliability Applications

**1 Scope** This standard prescribes practices for the characterization, qualification and acceptance requirements of compliant press-fit technology for printed boards that cover the manufacturability and reliability needs for high reliability applications intended for use in harsh environments such as automotive and aerospace.

Additional requirements for aerospace applications in Appendix B may apply.

**1.1 Purpose** This standard prescribes practices for the characterization, qualification and acceptance requirements of compliant press-fit technology for printed boards.

Standards may be updated at any time, including with the use of amendments. The use of an amendment or newer revision is not automatically required. The revision in effect **shall** be as specified by the user.

#### 1.2 Classification

#### **CLASS 1 General Electronic Products**

Includes products suitable for applications where the major requirement is function of the completed assembly.

#### **CLASS 2 Dedicated Service Electronic Products**

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically, the end-use environment would not cause failures.

#### **CLASS 3 High Performance/Harsh Environment Electronic Products**

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

All requirements in this standard pertain to IPC Class 3. When this standard is contractually required, IPC Class 3 requirements shall be adopted for all other contractually required standards.

**1.3 Measurement Units** This standard uses International System of Units (SI units) per ASTM SI10, IEEE/ASTM SI 10, Section 3 [Imperial English equivalent units are in brackets for convenience]. The SI units used in this standard are millimeters (mm) [in] for dimensions and dimensional tolerances, Celsius (°C) [°F] for temperature and temperature tolerances, grams (g) [oz] for weight, and lumens (lm) [footcandles] for illuminance.

**Note:** This standard uses other SI prefixes (ASTM SI10, Section 3.2) to eliminate leading zeroes (for example, 0.0012 mm becomes 1.2  $\mu$ m) or as an alternative to powers-of-ten (3.6 x 10<sup>3</sup> mm becomes 3.6 m).

- **1.3.1 Verification of Dimensions** When an inspection is done on an assembly, measuring dimensions and determining percentages listed in the standard are not required unless there is a doubt or a question is raised about the acceptance of the product. When there is a doubt or a question is raised, then a referee determination should be implemented, at which time measurements should be made or percentages calculated using the referee magnifications defined in the Standard. For determining conformance to the specifications in this standard, round all observed or calculated values "to the nearest unit" in the last right-hand digit used in expressing the specification limit, in accordance with the rounding method of ASTM Practice E29. For example, specifications of 2.5 mm max, 2.50 mm max, or 2.500 mm max, round the measured value to the nearest 0.1 mm, 0.01 mm, or 0.001 mm, respectively, and then compare to the specification number cited.
- **1.4 Definition of Requirements** The words "shall" or "shall not" are used in the text of this document wherever there is a requirement for materials, preparation, process control or acceptance.

The word "should" reflects recommendations and is used to reflect general industry practices and procedures for guidance only.

Line drawings and illustrations are depicted herein to assist in the interpretation of the written requirements of this standard. The text takes precedence over the figures.